

WHAT IS CLAIMED IS:

1. A manufacturing method of a module card comprising steps of:
providing a base board having a golden finger;
mounting a chip on said base board for electrically connecting to said
5 golden finger; and
forming a packing layer on said chip for forming said module card.
2. A manufacturing method according to Claim 1 wherein said base
board includes a first surface and a second surface for mounting a
plurality of said chips on said first surface and said second surface.
- 10 3. A manufacturing method according to Claim 1 wherein said base
board includes a plurality of package areas for packing a plurality of
said module cards once.
4. A manufacturing method according to Claim 1 wherein said packing
layer includes a material of epoxy mold compound.
- 15 5. A manufacturing method according to Claim 1 wherein said base
board is a circuit board, and said circuit board is a printed circuit board.
6. A module card comprising:
a base board;
a chip mounting on a surface of said base board;
20 a golden finger on said board and electrically connecting to said chip;
and
a packing layer forming on said chip for covering said chip.
7. A module card according to Claim 6 wherein said packing layer
includes a material of epoxy mold compound.
- 25 8. A module card according to Claim 6 wherein said surface of said base
board includes a first surface and a second surface for packing a
plurality of said chips.

9. A module card according to Claim 6 wherein said module card is double sided.

10. A module card according to Claim 6 wherein said base board is a circuit board, and said circuit board is a printed circuit board.

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